



Customer Information Notification

202102007I : NXP Final Test Site Relocation Initiative: ATTJ to ATTJ Building 2 (ATTJ-B2) - Phase1

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 08, 2021 **Effective date:** Mar 11, 2021

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Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

NXP Semiconductors announces the ATTJ Final Test Site Relocation Initiative from the current NXP ATTJ, Tianjin, China test site to local, nearby (2.5km away) ATTJ-B2 test site, creating a consolidated ATTJ Test Center of Excellence. The associated Test Backend Shipping / Packing Operations will relocate to the ATTJ-B2 site as well. This NXP Initiative will be a phased / ramped relocation activity, spanning from Mar-2021 (CIN #202102007I effective date) until all Final Test platform types have been relocated to the ATTJ-B2.

This major, strategic NXP initiative ensures future scalability of NXP ATTJ backend manufacturing sites, ATTJ main factory and new ATTJ-B2, to support current and future business. The current ATTJ main factory manufacturing floor space is fully utilized. Final Test and Test Backend Shipping / Packing Operations must be migrated to the new ATTJ-B2 Test Center of Excellence, while the existing ATTJ main factory will be exclusive for assembly and other non-Final Test operations. This initiative allows growth opportunities for both ATTJ manufacturing buildings for customer supply assurance.

The ATTJ-B2 is located 2.5 km Southeast from the current ATTJ main factory site, and adheres to the same ATTJ criteria: 100k clean room rating, temperature / humidity / ESD controls, and quality accreditations.

All current ATTJ main factory Final Test equipment (hardware / software), test flows, test programs, policies, procedures, and personnel will be relocated to the new ATTJ-B2. Absolutely no impact to product form, fit, function or reliability.

Please see the attached documents for additional details.

Reason

Qualification of NXP ATTJ, Tianjin, China new ATTJ-B2 is a new NXP strategic initiative to create a consolidated ATTJ Test Center of Excellence for Final Test Site and associated Test Backend Shipping / Packing Operations for current and future customer supply assurance.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Affected Part Numbers

MC56F81646VLF

MC56F81648VLH

MC56F81666VLF

MC56F81668VLH

MC56F81746MLF

MC56F81746VLF

MC56F81748MLH

MC56F81748VLH

MC56F81766MLF

MC56F81766VLF

MC56F81768MLH

MC56F81768VLH

MC56F81866VLF

MC56F81868VLH

MC9S08PL8SCTJR